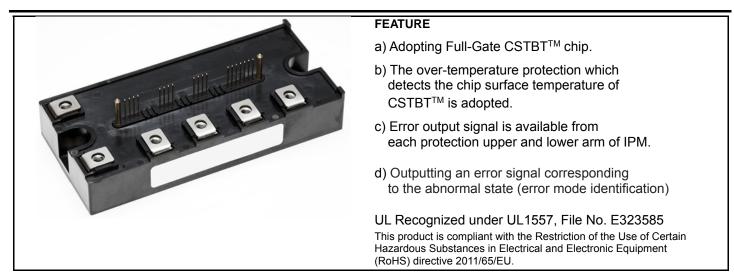


<Intelligent Power Modules>

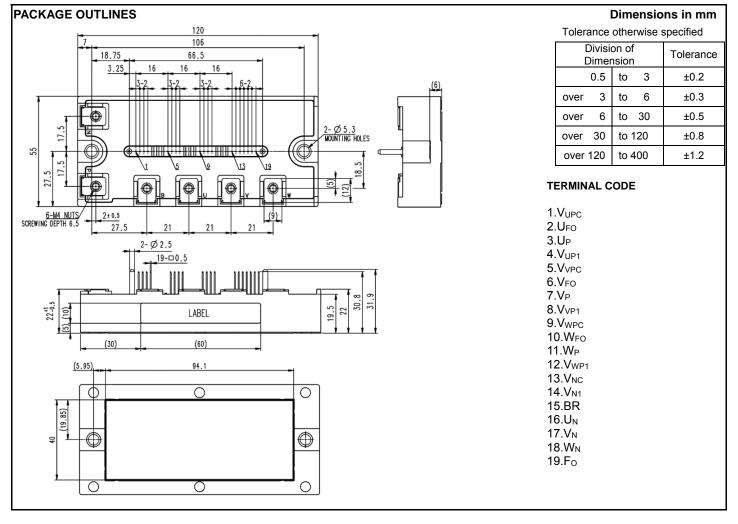
PM150RG1B065

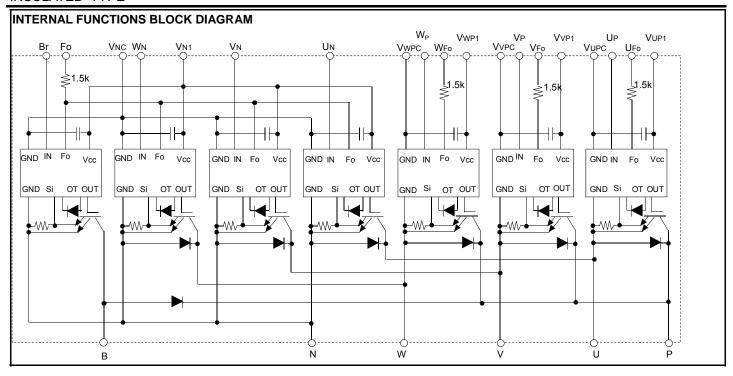
FLAT-BASE TYPE INSULATED PACKAGE



APPLICATION

General purpose inverter, servo drives and other motor controls





MAXIMUM RATINGS (Tvj = 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
lc	Collector Current	T _c =25 °C	150	^
I _{CRM}	Collector Current	Pulse	300	A
P _{tot}	Total Power Dissipation	T _c =25 °C	480	W
l _E	Emitter Current	T _C =25 °C	150	^
I _{ERM}	(Free-wheeling Diode Forward current)	Pulse	300	A
Tvj	Junction Temperature		-20 ~ +150	°C

*: Tc measurement point is just under the chip.

BRAKE PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
I _C	Collector Current	T _c =25 °C	75	^
I _{CRM}		Pulse	150	A
P _{tot}	Total Power Dissipation	T _C =25 °C	297	W
V _{R(DC)}	Diode Rated Reverse DC Voltage	T _c =25 °C	650	V
l _F	Diode Forward Current	T _c =25 °C	75	А
Tj	Junction Temperature		-20 ~ +150	°C

*: Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Conditions	Ratings	Unit
V _D	Supply Voltage	Applied between: V_{UP1} - V_{UPC} , V_{VP1} - V_{VPC} , V_{WP1} - V_{WPC} , V_{N1} - V_{NC}	20	V
V _{CIN}	Input Voltage	Applied between: U _P -V _{UPC} , V _P -V _{VPC} , W _P -V _{WPC} , U _N , V _N , W _N , Br -V _{NC}	20	V
V _{FO}	Fault Output Supply Voltage	Applied between: U_{FO} - V_{UPC} , V_{FO} - V_{VPC} , W_{FO} - V_{WPC} , FO- V_{NC}	20	V
I _{FO}	Fault Output Current	Sink current at U_{FO} , V_{FO} , W_{FO} , Fo terminals	20	mA

TOTAL SYSTEM

Symbol	Parameter	Conditions	Ratings	Unit			
V _{CC(PROT)}	Supply Voltage Protected by SC	V _D =13.5 V~16.5 V, Inverter Part, Tvj=+125°C start	400	V			
T _{stg}	Storage Temperature	-	-40 ~ +125	°C			
Tc	Operating Case Temperature	-	-20 ~ +125	°C			
V _{isol}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V			

*: Tc measurement point is just under the chip.

THERMAL RESISTANCE

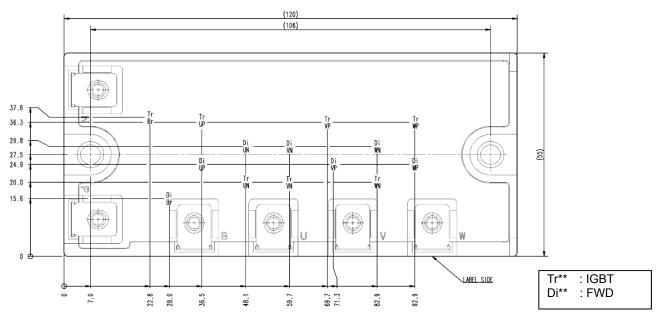
Symbol	Deremeter	Conditions	Limits			Unit
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	Thermal Resistance	Inverter, Junction to case, IGBT, per 1 element (Note1)	-	-	0.26	
R _{th(j-c)D}		Inverter, Junction to case, FWD, per 1 element (Note1)	-	-	0.42	K/W
R _{th(j-c)Q}		Brake, Junction to case, IGBT, per 1 element (Note1)	-	-	0.42	rv vv
R _{th(j-c)D}		Brake, Junction to case, FWD, per 1 element (Note1)	-	-	0.68	
$R_{th(c-s)}$	Contact Thermal Resistance	Case to heat sink, per 1 module,	-	14.4	_	K/kW
		Thermal grease applied (Note.1, 2)			-	IVEN

Note1. If you use this value, $R_{th(s-a)}$ should be measured just under the chips.

Note2. Typical value is measured by using thermally conductive grease of λ =0.9W/(m·K), D_(C-S)=50 µm.

CHIP LOCATION (Top view)

Dimension in mm, torelance: ±1mm



ELECTRICAL CHARACTERISTICS (Tvj= 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Condition	Conditions			Limits		Unit
Symbol	Falameter	Condition				Тур.	Max.	
			Tui-25 °C	Terminal	-	-	1.9	
V	Collector-Emitter Saturation Voltage	V _D =15 V, I _C =150 A	Tvj=25 °C	Chip	-	1.25	-	v
V _{CEsat}		V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.1	v
		V _{CIN} =0 V, Pulsed, (Fig. I)	1 VJ=125 C	Chip	-	1.33	-	
		V _D =15 V, I _E =150A, Tvj=25 °	Tui=25 °C	Terminal	-	-	2.0	v
V	Emitter-Collector Voltage		1 vj=25 C	Chip	-	1.40	-	
V _{EC}		V _{CIN} = 15 V, pulsed, (Fig.2) Tvj=125 °C	Tyi-125 °C	Terminal	-	-	2.1	
			Chip	-	1.45	-		
t _{on}		V_{D} =15 V, V_{CIN} =0 V \leftrightarrow 15 V,		0.30	0.80	1.20		
t _{rr}		V _{cc} =300 V, I _c =150A,		-	0.27	0.65		
t _{c(on)}	Switching Time	Tvj=125 °C,			-	0.24	0.75	μs
t _{off}		Inductive Load		- 0.82	0.82	2.30		
t _{c(off)}		(Fig.3, 4)		-	0.13	0.40		
	Collector-Emitter Cut-off Current	V _{CE} =V _{CES} , V _D =15 V,		Tvj=25 °C	-	-	1	m۸
I _{CES}			Tvj=125 °C	-	-	10	mA	

BRAKE PART

Cumbal	Parameter	Conditions		Limits			Unit	
Symbol	Parameter	Condition	Conditions		Min.	Тур.	Max.	Unit
V _{CEsat}		V _D =15 V, I _C =75A	Tvj=25 °C	Terminal	-	-	1.75	
		v _D =13 v, 1c=73A	10]-23 0	Chip	-	1.25	-	V
	Collector-Emitter Saturation Voltage	V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.0	
				Chip	-	1.33	-	
		I _F =75A	Tvj=25 °C	Terminal	-	-	1.95	- V
V	Diada Farward Valtage			Chip	-	1.40	-	
V _{FM}	Diode Forward Voltage		T : 105 00	Terminal	-	-	2.05	
			Tvj=125 °C	Chip	-	1.45	-	
		V _{CE} =V _{CES} , V _D =15 V, V _{CIN} =15 V (Fig.5)		Tvj=25 °C	-	-	1	
I _{CES}	Collector-Emitter Cut-off Current			Tvj=125 °C	-	-	10	mA

ELECTRICAL CHARACTERISTICS (Tvj = 25°C, unless otherwise noted)

CONTROL PART

Symbol	Parameter Conditions				Limits		
Symbol	Parameter	Conditions	Conditions		Тур.	Max.	Unit
		V _D =15 V, V _{CIN} =15 V	V _{P1} -V _{PC}	-	4	6	
	Circuit Current	$v_{\rm D}$ = 15 V, $v_{\rm CIN}$ = 15 V	V _{N1} -V _{NC}	-	16	24]
ID		V_{D} =15 V, V_{CIN} =0 V \leftrightarrow 15 V, V_{CC} =400 V	V _{P1} -V _{PC}	-	20	24	mA
		l _c =0A, Tvj=125 °C, f _c ≤20kHz	V _{N1} -V _{NC}	-	72	85	1
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8	v
$V_{th(OFF)}$	Input OFF Threshold Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, W_{N},$	Br-V _{NC}	1.7	2.0	2.3	
S.C.	Short Circuit Trip Loval		Inverter	300	-	-	•
SC	Short Circuit Trip Level	-20≤Tvj≤125 °C, V _D =15 V (Fig.3, 6)	Brake	150	-	-	A
t _{d(SC)}	Short Circuit Current Delay Time	V _D =15 V, Tvj=125 °C (Fig.3, 6)		-	2.0	-	μs
ОТ	Over Temperature Distoction	Detect temperature of IGBT chip surface	Trip level	150	-	-	<u></u>
OT _(hys)	Over Temperature Protection		Hysteresis	-	20	-	
UVt	Supply Circuit		Trip level	11.0	12.0	12.7	v
UVr	Under-Voltage Protection		Reset level	-	12.5	-	
I _{FO(H)}	Fault Output Current			-	-	0.01	
I _{FO(L)}		V _D =15 V, V _{FO} =15 V (Note3)		-	10	15	mA
			ОТ	-	8.0	-	
t _{FO}	Fault Output Pulse Width	V _D =15 V (Note3)	UV	-	4.0	-	ms
			SC	-	2.0	-	

Note3. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

MECHANICAL RATINGS AND CHARACTERISTICS

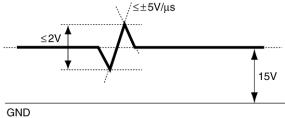
Symbol	Parameter	Conditions	Limits			Unit
		Conditions		Тур.	Max.	Unit
Ms	Mounting Torque	Mounting part screw : M5	2.5	3.0	3.5	N•m
Mt	Mounting Torque	Main terminal part screw : M4	1.5	1.7	2.0	IN*III
m	mass	-	-	260	-	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Conditions	Recommended value	Unit
Vcc	Supply Voltage	Applied across P-N terminals	≤ 400	V
V _D	Control Supply Voltage	Applied between : Vup1-Vupc, Vvp1-Vvpc, Vwp1-Vwpc,Vn1-Vnc (Note4)	15.0±1.5	V
V _{CIN(ON)}	Input ON Voltage	Applied between :	≤ 0.8	v
$V_{CIN(OFF)}$	Input OFF Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, W_{N}, Br\text{-}V_{NC}$	≥ 9.0	v
f _{PWM}	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.0	μs

This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

Note4. With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5$ V/µs, Variation ≤ 2 V peak to peak



PRECAUTIONS FOR TESTING

VD(a

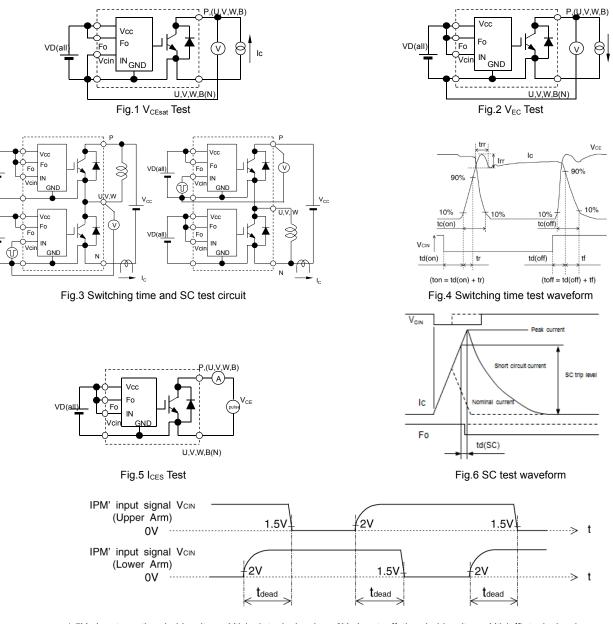
VD(all

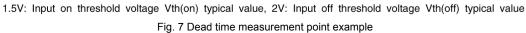
1. Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.

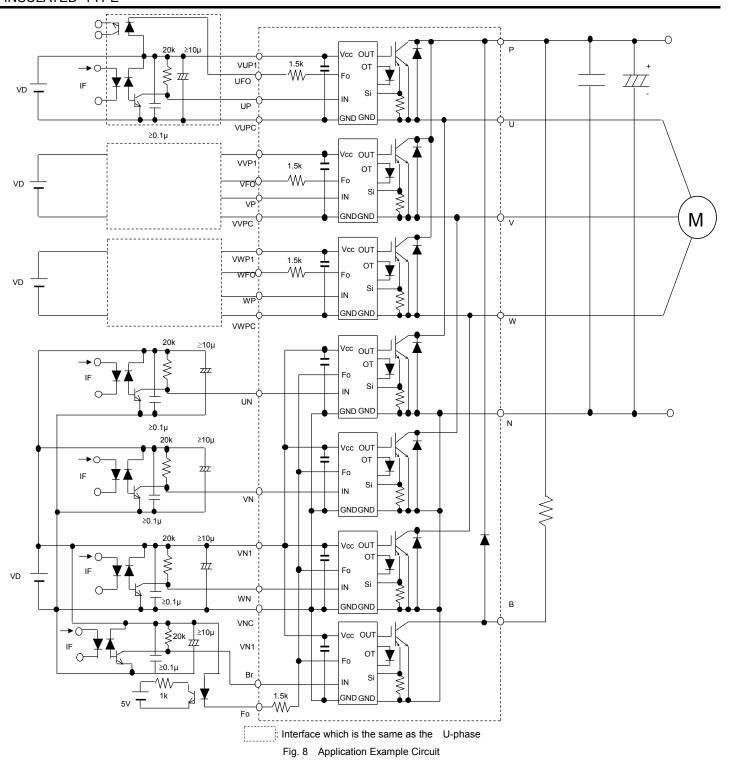
After this, the specified ON and OFF level setting for each input signal should be done.

2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V_{CES} rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)





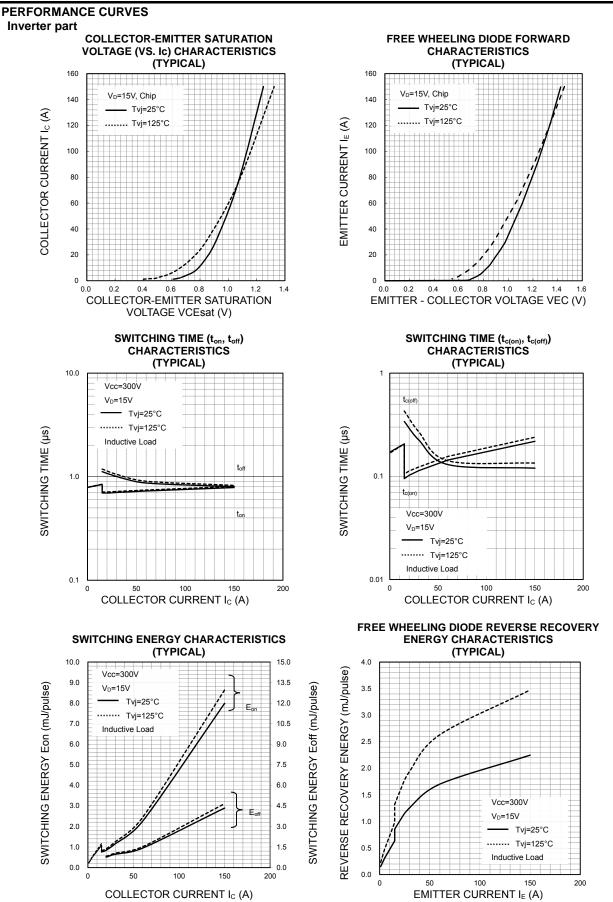


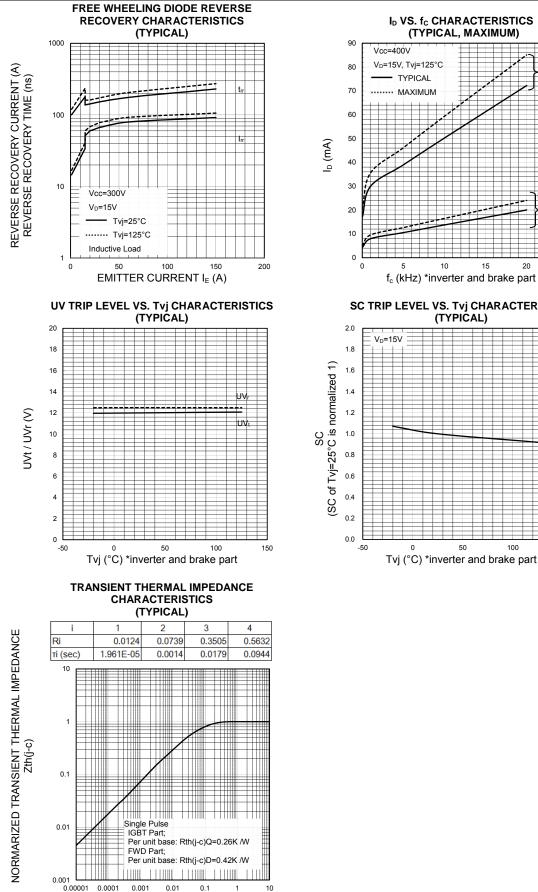
NOTES FOR STABLE AND SAFE OPERATION ;

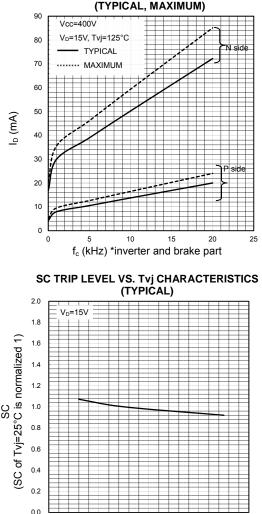
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t_{PLH} , $t_{PHL} \le 0.8 \mu$ s, Use High CMR type.
- Slow switching opto-coupler: CTR > 100% (*can be applied to Brake part input signal, in this case, resistor should be selected properly).
- Use 4 isolated control power supplies (V_D). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

<Intelligent Power Modules> PM150RG1B065 HIGH POWER SWITCHING USE









50

100

150

0.0001

0.001

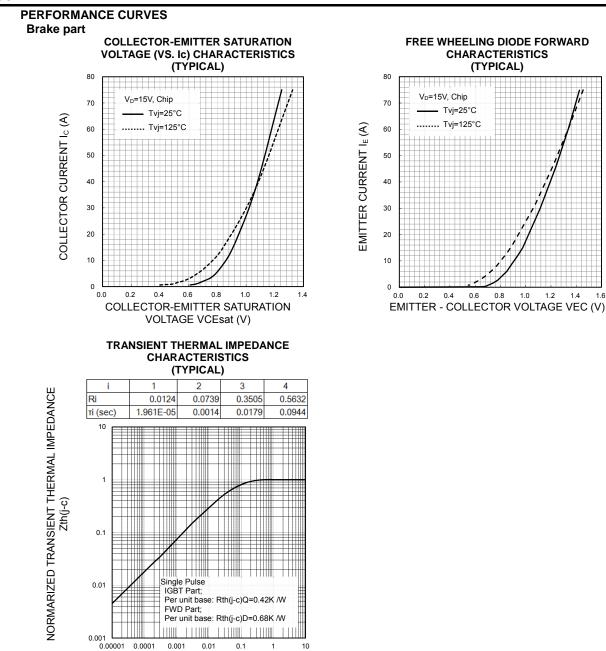
0.01

TIME (s)

0.1

1

10



TIME (s)

1.6

Keep safety first in your circuit designs!

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